ICS 25.040.40, 35.100.05 SLOVENSKÁ TECHNICKÁ NORMA August 2023

STN

Integrácia softvérového nástroja (FDI®) Časť 4: Programové balíky FDI

STN
EN IEC 62769-4

18 4012

Field Device Integration (FDI) - Part 4: FDI Packages

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR Č. 07/23

Obsahuje: EN IEC 62769-4:2023, IEC 62769-4:2023

Oznámením tejto normy sa od 10.05.2026 ruší
STN EN IEC 62769-4 (18 4012) z júla 2021

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EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN IEC 62769-4

May 2023

ICS 25.040.40; 35.100.05

Supersedes EN IEC 62769-4:2021

English Version

Field Device Integration (FDI®) - Part 4: FDI Packages (IEC 62769-4:2023)

Intégration des appareils de terrain (FDI®) - Partie 4:
Paquetages FDI
(IEC 62769-4:2023)

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(IEC 62769-4:2023)

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Ref. No. EN IEC 62769-4:2023 E

European foreword

The text of document 65E/857/CDV, future edition 3 of IEC 62769-4, prepared by SC 65E "Devices and integration in enterprise systems" of IEC/TC 65 "Industrial-process measurement, control and automation" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62769-4:2023.

The following dates are fixed:

• latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement	(dop)	2024-02-10
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In the official version, for Bibliography, the following notes have to be added for the standard indicated:

IEC 61784-1-1:2023	NOTE	Approved as EN IEC 61784-1-1:2023 (not modified)
IEC 61784-1-3:2023	NOTE	Approved as EN IEC 61784-1-3:2023 (not modified)
IEC 61784-1-9:2023	NOTE	Approved as EN IEC 61784-1-9:2023 (not modified)
IEC 62591	NOTE	Approved as EN 62591
IEC 62734	NOTE	Approved as EN 62734

Annex ZA
(normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cencenelec.eu.

Publication	Year	Title	EN/HD	Year
IEC 61804-3	-	Devices and integration in enterprise systems - Function blocks (FB) for process control and electronic device description language (EDDL) - Part 3: EDDL syntax and semantics	EN IEC 61804-3	-
IEC 61804-5	2020	Devices and intergration in enterprise systems - Function blocks (FB) for process control and electronic device description language (EDDL) - Part 5: EDDL Builtin library	EN IEC 61804-5	2020
IEC 62769-1	-	Field Device Integration (FDI®) - Part 1: Overview	EN IEC 62769-1	-
IEC 62769-2	-	Field Device Integration (FDI®) - Part 2: Client	EN IEC 62769-2	-
IEC 62769-5	-	Field Device Integration (FDI®) - Part 5: FDI Information Model	EN IEC 62769-5	-
IEC 62769-6	-	Field Device Integration (FDI®) - Part 6: FDI Technology Mappings	EN IEC 62769-6	-
IEC 62769-7	-	Field Device Integration (FDI®) - Part 7: Communication Devices	EN IEC 62769-7	-
IEC 62769-1xx	series	Field device integration (FDI®) - Part 1xx-y: Profiles	-	-
ISO/IEC 11578	-	Information technology - Open Systems Interconnection - Remote Procedure Call (RPC)	-	-
ISO/IEC 29500-2	2021	Document description and processing languages - Office Open XML file formats - Part 2: Open packaging conventions	-	-
ISO 639-1	-	Codes for the representation of names of languages - Part 1: Alpha-2 code	-	-
ISO 32000-1	-	Document management - Portable document format - Part 1: PDF 1.7	-	-

Publication	Year	Title	EN/HD	Year
Dublin Core Metadata Initiative	2020	DCMI Metadata Terms	-	-
FCG TS10099	-	Field Device Integration (FDI®) - Technology Management	-	-
FIPS 140-3	2019	Security Requirements for Cryptographic Modules	-	-
ETSI EN 319 132-1	-	Electronic Signatures and Infrastructures (ESI); XAdES digital signatures; Part 1: Building blocks and XAdES baseline signatures	-	-
ETSI TS 101 733	-	Electronic Signatures and Infrastructures (ESI); CMS Advanced Electronic Signatures (CAdES)	-	-

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INTERNATIONAL STANDARD

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Field Device Integration (FDI®) – Part 4: FDI Packages

Intégration des appareils de terrain (FDI®) – Partie 4: Paquetages FDI

IEC 62769-4:2023-04(en-fr)

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IEC Secretariat
3, rue de Varembé
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
info@iec.ch
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Field Device Integration (FDI®) – Part 4: FDI Packages

Intégration des appareils de terrain (FDI®) – Partie 4: Paquetages FDI

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FIELD DEVICE INTEGRATION (FDI®) –

Part 4: FDI® Packages

FOREWORD

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IEC 62769-4 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation. It is an International Standard.

This third edition cancels and replaces the second edition published in 2021. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) added DocumentClass to Package Schema, Description of Feature Table and Documentation Catalog, individual schemas for Feature Table and Package Documentation Catalog, schema for UnitConversion, interactive download to device, and Feature Unit Conversion;
b) moved DocumentClass to Package Documentation Catalog Schema;
c) updated Description of Feature Table updated XML schema for Feature Table.

The text of this International Standard is based on the following documents:

Draft	Report on voting
65E/857/CDV	65E/914/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC 62769 series, published under the general title *Field device integration (FDI®)*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

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FIELD DEVICE INTEGRATION (FDI®) –

Part 4: FDI® Packages

1 Scope

This part of IEC 62769 specifies the FDI®[1] Packages. The overall FDI® architecture is illustrated in Figure 1. The architectural components that are within the scope of this document have been highlighted in this figure.

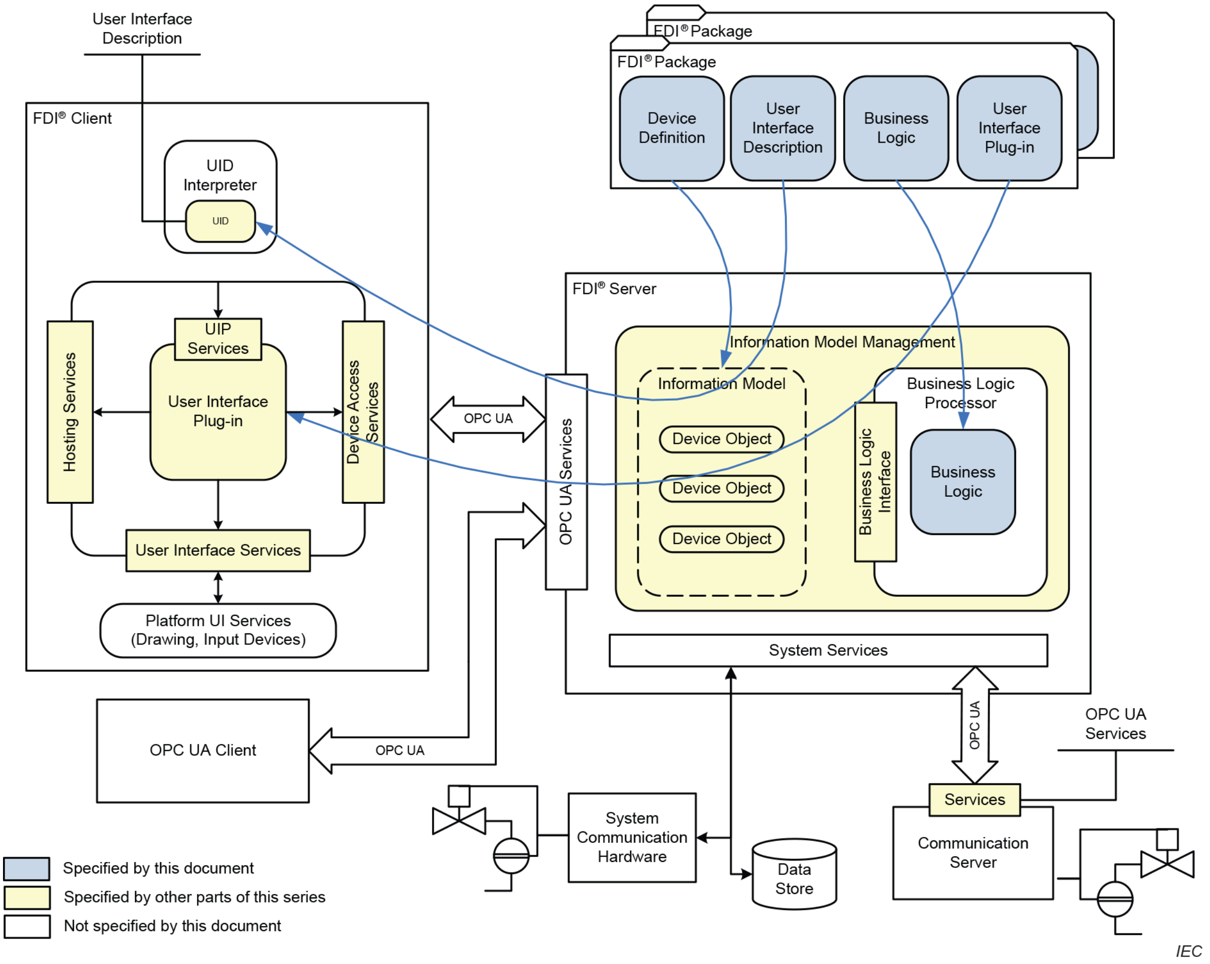

Figure 1 – FDI® architecture diagram

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies.

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IEC 62769-7, *Field Device Integration (FDI®) – Part 7: Communication Devices*

IEC 62769-1xx (all parts), *Field Device Integration (FDI®) – Part 1xx-y: Profiles*

ISO/IEC 11578, *Information technology – Open Systems Interconnection – Remote Procedure Call (RPC)*

ISO/IEC 29500-2:2021, *Document description and processing languages – Office Open XML file formats – Part 2: Open packaging conventions*

ISO 639-1, *Codes for the representation of names of languages – Part 1: Alpha-2 code*

ISO 32000-1, *Document management – Portable document format – Part 1: PDF 1.7*

Dublin Core Metadata Initiative: DCMI Metadata Terms, 2020

FCG TS10099, *Field Device Integration (FDI®) – Technology Management*

FIPS 140-3:2019, *Security Requirements for Cryptographic Modules*

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